

WAFER-TGL-U

3.5" SBC supports Intel® Tiger Lake-UP3 Core I™ Celeron® Processor, with HDMI™, DP, iDPM, triple 2.5 GbE Lan port, USB 3.2, M.2, SATA 6Gb/s, COM, Audio and RoHS, -10°C ~60°C



Features

1. 3.5" SBC with Intel® Tiger Lake-UP3 on board SOC processor, support SO-DIMM DDR4-3200 memory
2. Support Quadruple independent display: 2 x HDMI™ 1.4, 1 x DP 1.4, 1 x iDPM
3. High-speed I/O interface: 4 x USB 3.2 gen 2 (10Gb/s), SATA (6Gb/s)
4. Support three Intel® I225V/I226V 2.5GbE network port
5. Support M.2 A Key, B key extension

Specifications

| System | |
|-----------------------------|---|
| CPU | 11th Gen. Intel® mobile Tiger Lake-UP3 on board processor |
| | Intel® Core™ i7-1185G7E (up to 4.4GHz, quad-core, 12M Cache, TDP=28/15/12W) |
| | Intel® Core™ i5-1145G7E (up to 4.1GHz, quad-core, 8M Cache, TDP=28/15/12W) |
| | Intel® Core™ i3-1115G4E (up to 3.9GHz, dual-core, 6M Cache, TDP=28/15/12W) |
| | Intel® Celeron® 6305E (up to 1.8GHz, dual-core, 4M Cache, TDP=15W) |
| Memory | One 260-pin 3200 MHz DDR4 SO-DIMMs support up to 32 GB |
| Memory Max. | up to 32GB |
| Cooling method / System Fan | 1 x System fan connector (1x4 pin, P=2.54) |
| Storage | |
| Storage | 1 x SATA : 6Gb/s with 5V SATA power connector |
| | 1 x M.2(NGFF) : B Key(2242/3052) with PCIe Gen3 x2,support NVME storage |
| I/O Interface | |
| Display Output | 2 x HDMI™ : up to 4096 x 2160@30Hz |
| | 1 x Display Port : up to 4096 x 2160@60Hz |
| | 1 x iDPM : IEI iDPM 3040 slot (only for IEI eDP/LVDS/VGA module) |
| Ethernet | 3 x LAN - |
| | LAN1: Intel® I225V/I226V 2.5GbE controller |
| | LAN2: Intel® I225V/I226V 2.5GbE controller |
| | LAN3: Intel® I225V/I226V 2.5GbE controller |
| Audio | 1 x HD Audio : 1 x iAUDIO, support IEI AC-KIT-888S Audio Module (2 x 5 pin) |
| I/O Interface | 1 x Internal RS-232 : 2x5 pin, P=2.0 |
| | 2 x Internal RS-232/422/485 : 2x5 pin, P=2.00 ,RS-485 support AFC |
| | 2 x Internal USB 2.0 : 2x4 pin, P=2.00 |
| | 1 x DIO : 12-bit digital I/O (2x7 pin, P=2.0) |
| | 4 x External USB 3.2 Gen2x1 : 10Gb/s |
| Expansion | 2 x M.2(NGFF) - |
| | 1 x M.2 A key (2230) with PCIe Gen3 x1/USB 2.0 |
| | 1 x M.2 B Key (2242/3052) for 5G with PCIe Gen3 x2/USB 2.0 |
| Other Features | |
| TPM | Intel® PTT(TPM 2.0) |
| Power | |
| Power Supply | +12V DC input power (AT/ATX mode) |

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|-----------------------|--------------------------|
| Environment | |
| Operating Temperature | 0°C ~ 60°C |
| Storage Temperature | -20°C ~ 70°C |
| Humidity | 5% ~ 95%, non-condensing |
| Certifications | |
| Safety & EMC | CE/FCC compliant |

Ordering Information

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| WAFER-TGL-U-i7-R11 | 3.5" SBC with Intel® Tiger Lake-UP3 Core™ i7-1185G7E Processor,DDR4 SO-DIMM,12V DC input,Quad Display,Triple M.2 with A/B key,Triple Intel® 2.5 GbE,SATA,USB3.2,SoC,RoHS |
| WAFER-TGL-U-i5-R11 | 3.5" SBC with Intel® Tiger Lake-UP3 Core™ i5-1145G7E Processor,DDR4 SO-DIMM,12V DC input,Quad Display,Triple M.2 with A/B key,Triple Intel® 2.5 GbE,SATA,USB3.2,SoC,RoHS |
| WAFER-TGL-U-i3-R11 | 3.5" SBC with Intel® Tiger Lake-UP3 Core™ i3-1115G4E Processor,DDR4 SO-DIMM,12V DC input,Quad Display,Triple M.2 with A/B key,Triple Intel® 2.5 GbE,SATA,USB3.2,SoC,RoHS |
| WAFER-TGL-U-CE-R11 | 3.5" SBC with Intel® Tiger Lake-UP3 Celeron 6305E Processor,DDR4 SO-DIMM,12V DC input,Quad Display,Triple M.2 with A/B key,Triple Intel® 2.5 GbE,SATA,USB3.2,SoC,RoHS |

Packing List

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|---------------------------------------|----------------|
| 1 x WAFER-TGL-U single board computer | 1 x SATA cable |
| 1 x I/O shielding | 1 x QIG |